

PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10008958	FILING DATE 12/05/2001	CLASS 257	SUBCLASS 620	GAU 2814	EXAMINER N. HA
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\*\*APPLICANTS: Sasaki Miki; Minami Toshifumi;

\*\*CONTINUING DATA VERIFIED:

THIS APPLICATION IS A CON OF 09/135,740 08/18/1998

\*\* FOREIGN APPLICATIONS VERIFIED:

JAPAN 9-234875 08/29/1997

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed 33 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no
Verified and Acknowledged Examiners's initials		

TITLE : Semiconductor device and method for manufacturing the same incorporating a dicing technique for wafer separation and method for manufacturing the same  
ATTORNEY DOCKET NO  
FCCM/PAT/TM-PTO-430L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
TERMINAL DISCLAIMER		Primary Examiner	Application Examiner	
PREPARED FOR ISSUE				
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